

IN THE CLAIMS:

Claims 1 through 20. (Canceled)

21. (Currently Amended) A method for placing a multitude of shaped parts of solder material on a bond pad arrangement of a substrate, said bond pad arrangement comprising a multitude of bond pads, and for subsequent re-melting of the shaped parts of solder material on the bond pads, method comprising the steps of:

5 arranging a template device, comprising a multitude of template apertures for accommodating shaped parts of solder material opposite a substrate comprising a bond pad arrangement, such that the shaped parts of solder material are associated with the individual bond pads;

10 applying laser energy to the shaped parts of solder material accommodated in the template apertures using a swivelling mirror and a laser device arranged at the rear of the template device such that said laser energy is applied to the shaped parts of solder material through the template device;

15 selecting shaped parts of solder material from a bulk of shaped parts of solder material accommodated in the template device by filling the template apertures arranged in an aperture screen.

22. (Canceled)

23. (Currently Amended) The method according to claim ~~[[21]]~~ 44, further comprising the steps of:

filling the template apertures which are arranged in an aperture screen of the template device to select the shaped parts of solder material from a quantity of shaped parts of solder material outside the template device.

24. (Previously presented) The method according to one claim 21, further comprising the steps of:

scanning of the template apertures using an optical scanning device for detecting shaped parts of solder material, prior to the application of laser energy to the shaped parts of solder material.

25. (Previously presented) The method according to claim 24, wherein, application of laser energy to the shaped parts of solder material takes place via the optical scanning device.

26. (Currently amended) The method according to claim ~~2221~~, wherein, said step of filling of the template apertures arranged in the aperture screen of the template device takes place using a filling chamber movable over the aperture screen, said filling chamber being open towards the aperture screen.

27. (Currently amended) The method according to claim ~~2221~~, wherein, said step of

filling of the template apertures arranged in the aperture screen of the template device takes place using a paddle-wheel device guided substantially in parallel to the surface of the aperture screen, rotating on a movement axis.

28. (Previously presented) The method according to claim 23, wherein, said step of filling of the template apertures arranged in the aperture screen of the template device, takes place by means of pressure below atmospheric.

29. (Previously presented) The method according to claim 21, further comprising the steps of:

exerting pressure on the shaped parts of solder material accommodated in the template apertures for establishing contact with the bond pads by applying pressure above atmospheric pressure.

30. (Previously presented) A device for placing a multitude of shaped parts of solder material on a bond pad arrangement of a substrate, said bond pad arrangement comprising a multitude of bond pads, and for subsequent re-melting of the shaped parts of solder material on the bond pads, the device comprising:

a template device with a container for accommodating a quantity of shaped parts of solder material, said container comprising a transparent rear wall and a container wall forming an aperture screen for conveying shaped parts of solder material to the bond pad arrangement,

10 the aperture screen comprising a selecting device such that shaped parts of solder material which have been singled out from the quantity of shaped parts of solder material and allocated to individual bond pads of the bond pad arrangement, are arranged so as to be exposed, in template apertures of the aperture screen, and thus can be exposed to laser energy from the side of the template device which is turned away from the substrate by means of a laser device.

31. (Previously presented) The device according to claim 30, wherein, the selecting device is movable over the aperture screen.

32. (Previously presented) The device according to claim 31, wherein, the selecting device is a filling chamber which can be moved over the aperture screen, said filling chamber being open towards the aperture screen.

33. (Previously presented) The device according to claim 31, wherein, the selecting device is a paddle-wheel device movable over the aperture screen, with radially open transport compartments delimited by paddles of the paddle-wheel device.

34. (Previously presented) The device according to claim 30, wherein, the selecting device is accommodated in a space closed by the template device with a rear wall opposite the aperture screen made transparent.

35. (Currently Amended) A device for placing a multitude of shaped parts of solder material on a bond pad arrangement of a substrate, said bond pad arrangement comprising a multitude of bond pads, and for subsequent re-melting of the shaped parts of solder material on the bond pads, the device comprising;

5 a template device with a selecting device, said template device including a housing with an aperture screen comprising a multitude of template apertures for accommodating shaped parts of solder material and a transparent rear wall, opposite the aperture screen, the diameter of the template apertures formed in the aperture screen being larger than the largest diameter of the shaped parts of solder material, and the distance between the aperture screen and the rear
10 wall being smaller than the smallest diameter of the shaped parts of solder material.

36, 37. (Canceled)

38. (Previously presented) The device according to claim 30, wherein, one or both of the wall structure of the aperture screen and the sidewall of the filling chamber, which can be moved over the aperture screen, is flexible across the area of the aperture screen.

39. (Previously presented) The device according to claim 38, wherein, the wall structure comprises at least three layers, with a flexible compression layer sandwiched between two wear-resistant surface layers.

40. (Previously presented) The device according to claim 39, wherein, the compression layer is made from a plastic material, and the surface layers are made from metal.

41. (Previously presented) A device in accordance with claim 35, wherein:
said transparent rear wall has a transparent portion that exposes a plurality of said template apertures to laser radiation.

42. (Previously presented) A device in accordance with claim 30, wherein:
said transparent rear wall has a transparent portion that exposes a plurality of said template apertures to laser radiation.

43. (Previously presented) A method in accordance with claim 21, further comprising:
swivelling said swivelling mirror to direct laser energy from said laser device to a plurality of said template apertures.

44. (New) A method for placing a multitude of shaped parts of solder material on a bond pad arrangement of a substrate, said bond pad arrangement comprising a multitude of bond pads, and for subsequent re-melting of the shaped parts of solder material on the bond pads, method comprising the steps of:

5 arranging a template device, comprising a multitude of template apertures for accommodating shaped parts of solder material opposite a substrate comprising a bond pad

arrangement, such that the shaped parts of solder material are associated with the individual bond pads;

10 applying laser energy to the shaped parts of solder material accommodated in the template apertures using a swivelling mirror and a laser device arranged at the rear of the template device such that said laser energy is applied to the shaped parts of solder material through the template device;

15 scanning the template apertures using an optical scanning device for detecting shaped parts of solder material, prior to the application of laser energy to the shaped parts of solder material, application of laser energy to the shaped parts of solder material taking place via the optical scanning device.